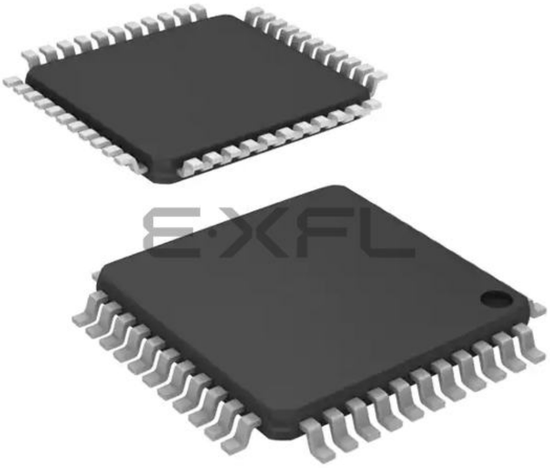
Microchip Technology - DSPIC33EP512MC504-E/PT Datasheet



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Applications of "Embedded - Microcontrollers"

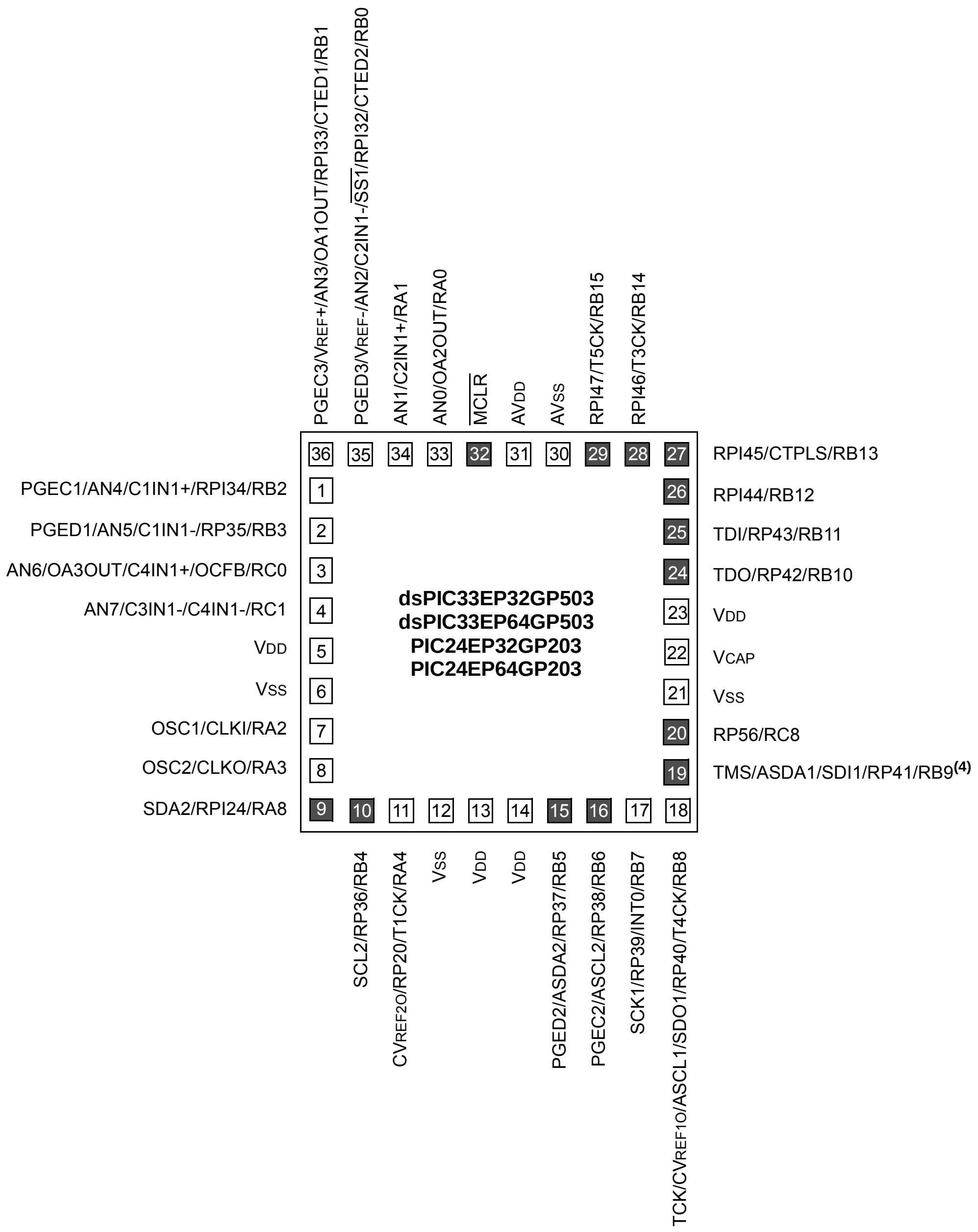
Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512mc504-e-pt

Email: info@E-XFL.COM
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Pin Diagrams (Continued)

36-Pin VTLA[1,2,3]

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

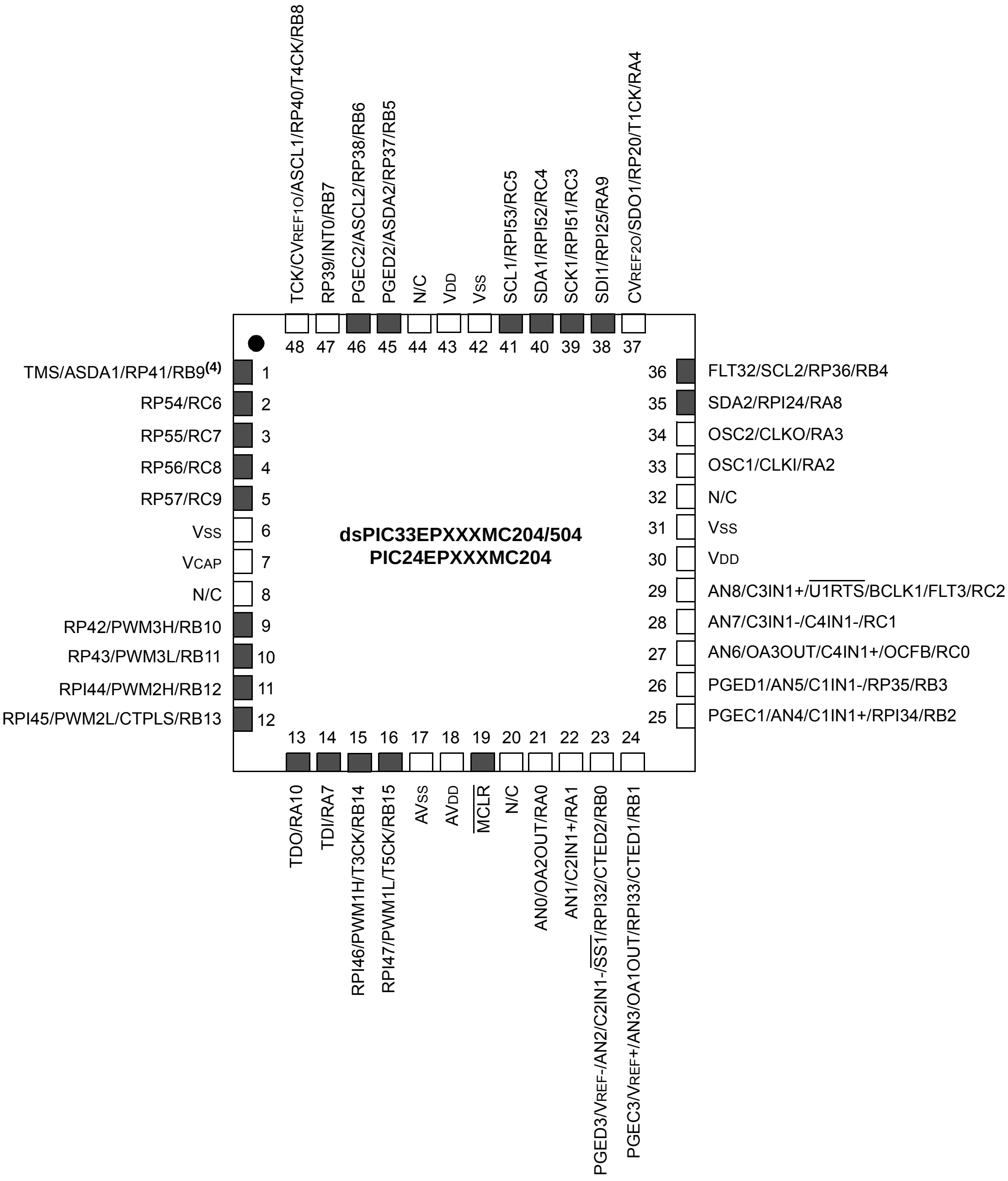
3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

Pin Diagrams (Continued)

48-Pin UQFN(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 2-5: SINGLE-PHASE SYNCHRONOUS BUCK CONVERTER

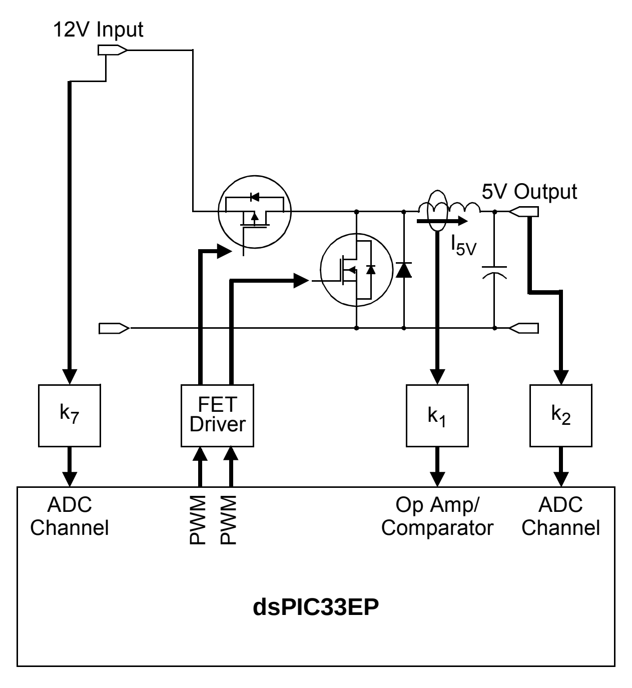


FIGURE 2-6: MULTIPHASE SYNCHRONOUS BUCK CONVERTER

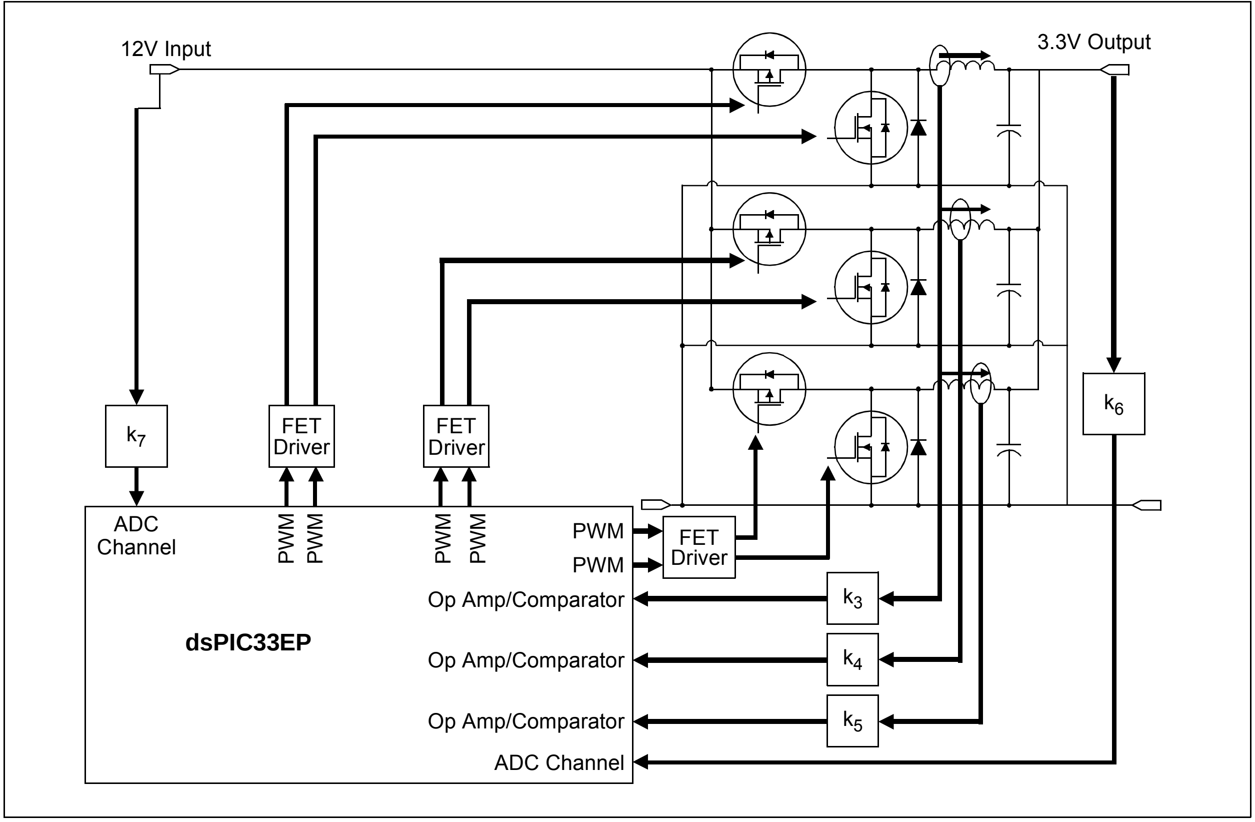


TABLE 4-5: INTERRUPT CONTROLLER REGISTER MAP FOR dsPIC33EPXXXGP50X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IFS0	0800	—	DMA1IF	AD1IF	U1TXIF	U1RXIF	SPI1IF	SPI1EIF	T3IF	T2IF	OC2IF	IC2IF	DMA0IF	T1IF	OC1IF	IC1IF	INT0IF	0000
IFS1	0802	U2TXIF	U2RXIF	INT2IF	T5IF	T4IF	OC4IF	OC3IF	DMA2IF	—	—	—	INT1IF	CNIF	CMIF	MI2C1IF	SI2C1IF	0000
IFS2	0804	—	—	—	—	—	—	—	—	—	IC4IF	IC3IF	DMA3IF	C1IF	C1RXIF	SPI2IF	SPI2EIF	0000
IFS3	0806	—	—	—	—	—	—	—	—	—	—	—	—	—	MI2C2IF	SI2C2IF	—	0000
IFS4	0808	—	—	CTMUIF	—	—	—	—	—	—	C1TXIF	—	—	CRCIF	U2EIF	U1EIF	—	0000
IFS6	080C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IF	0000
IFS8	0810	JTAGIF	ICDIF	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IFS9	0812	—	—	—	—	—	—	—	—	—	PTG3IF	PTG2IF	PTG1IF	PTG0IF	PTGWDTIF	PTGSTEPIF	—	0000
IEC0	0820	—	DMA1IE	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	T3IE	T2IE	OC2IE	IC2IE	DMA0IE	T1IE	OC1IE	IC1IE	INT0IE	0000
IEC1	0822	U2TXIE	U2RXIE	INT2IE	T5IE	T4IE	OC4IE	OC3IE	DMA2IE	—	—	—	INT1IE	CNIE	CMIE	MI2C1IE	SI2C1IE	0000
IEC2	0824	—	—	—	—	—	—	—	—	—	IC4IE	IC3IE	DMA3IE	C1IE	C1RXIE	SPI2IE	SPI2EIE	0000
IEC3	0826	—	—	—	—	—	—	—	—	—	—	—	—	—	MI2C2IE	SI2C2IE	—	0000
IEC4	0828	—	—	CTMUIE	—	—	—	—	—	—	C1TXIE	—	—	CRCIE	U2EIE	U1EIE	—	0000
IEC8	0830	JTAGIE	ICDIE	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC9	0832	—	—	—	—	—	—	—	—	—	PTG3IE	PTG2IE	PTG1IE	PTG0IE	PTGWDTIE	PTGSTEPIE	—	0000
IPC0	0840	—	T1IP<2:0>			—	OC1IP<2:0>			—	IC1IP<2:0>			—	INT0IP<2:0>			4444
IPC1	0842	—	T2IP<2:0>			—	OC2IP<2:0>			—	IC2IP<2:0>			—	DMA0IP<2:0>			4444
IPC2	0844	—	U1RXIP<2:0>			—	SPI1IP<2:0>			—	SPI1EIP<2:0>			—	T3IP<2:0>			4444
IPC3	0846	—	—	—	—	—	DMA1IP<2:0>			—	AD1IP<2:0>			—	U1TXIP<2:0>			0444
IPC4	0848	—	CNIP<2:0>			—	CMIP<2:0>			—	MI2C1IP<2:0>			—	SI2C1IP<2:0>			4444
IPC5	084A	—	—	—	—	—	—	—	—	—	—	—	—	—	INT1IP<2:0>			0004
IPC6	084C	—	T4IP<2:0>			—	OC4IP<2:0>			—	OC3IP<2:0>			—	DMA2IP<2:0>			4444
IPC7	084E	—	U2TXIP<2:0>			—	U2RXIP<2:0>			—	INT2IP<2:0>			—	T5IP<2:0>			4444
IPC8	0850	—	C1IP<2:0>			—	C1RXIP<2:0>			—	SPI2IP<2:0>			—	SPI2EIP<2:0>			4444
IPC9	0852	—	—	—	—	—	IC4IP<2:0>			—	IC3IP<2:0>			—	DMA3IP<2:0>			0444
IPC11	0856	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IPC12	0858	—	—	—	—	—	MI2C2IP<2:0>			—	SI2C2IP<2:0>			—	—	—	—	0440
IPC16	0860	—	CRCIP<2:0>			—	U2EIP<2:0>			—	U1EIP<2:0>			—	—	—	—	4440
IPC17	0862	—	—	—	—	—	C1TXIP<2:0>			—	—	—	—	—	—	—	—	0400
IPC19	0866	—	—	—	—	—	—	—	—	—	CTMUIP<2:0>			—	—	—	—	0040
IPC35	0886	—	JTAGIP<2:0>			—	ICDIP<2:0>			—	—	—	—	—	—	—	—	4400
IPC36	0888	—	PTG0IP<2:0>			—	PTGWDTIP<2:0>			—	PTGSTEPIP<2:0>			—	—	—	—	4440
IPC37	088A	—	—	—	—	—	PTG3IP<2:0>			—	PTG2IP<2:0>			—	PTG1IP<2:0>			0444

Legend: — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-9: INPUT CAPTURE 1 THROUGH INPUT CAPTURE 4 REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IC1CON1	0140	—	—	ICSIDL	ICTSEL<2:0>			—	—	—	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			`0000`
IC1CON2	0142	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL<4:0>					`000D`
IC1BUF	0144	Input Capture 1 Buffer Register																`xxxx`
IC1TMR	0146	Input Capture 1 Timer																`0000`
IC2CON1	0148	—	—	ICSIDL	ICTSEL<2:0>			—	—	—	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			`0000`
IC2CON2	014A	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL<4:0>					`000D`
IC2BUF	014C	Input Capture 2 Buffer Register																`xxxx`
IC2TMR	014E	Input Capture 2 Timer																`0000`
IC3CON1	0150	—	—	ICSIDL	ICTSEL<2:0>			—	—	—	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			`0000`
IC3CON2	0152	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL<4:0>					`000D`
IC3BUF	0154	Input Capture 3 Buffer Register																`xxxx`
IC3TMR	0156	Input Capture 3 Timer																`0000`
IC4CON1	0158	—	—	ICSIDL	ICTSEL<2:0>			—	—	—	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			`0000`
IC4CON2	015A	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL<4:0>					`000D`
IC4BUF	015C	Input Capture 4 Buffer Register																`xxxx`
IC4TMR	015E	Input Capture 4 Timer																`0000`

Legend: x = unknown value on Reset, — = unimplemented, read as ‘`0`’. Reset values are shown in hexadecimal.

5.2 RTSP Operation

RTSP allows the user application to erase a single page of memory and to program two instruction words at a time. See the General Purpose and Motor Control Family tables (Table 1 and Table 2, respectively) for the page sizes of each device.

For more information on erasing and programming Flash memory, refer to **"Flash Programming"** (DS70609) in the *"dsPIC33/PIC24 Family Reference Manual"*.

5.3 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. The processor stalls (waits) until the programming operation is finished.

For erase and program times, refer to Parameters D137a and D137b (Page Erase Time), and D138a and D138b (Word Write Cycle Time) in Table 30-14 in **Section 30.0 "Electrical Characteristics"**.

Setting the WR bit (NVMCON<15>) starts the operation and the WR bit is automatically cleared when the operation is finished.

5.3.1 PROGRAMMING ALGORITHM FOR FLASH PROGRAM MEMORY

Programmers can program two adjacent words (24 bits x 2) of program Flash memory at a time on every other word address boundary (0x000002, 0x000006, 0x00000A, etc.). To do this, it is necessary to erase the page that contains the desired address of the location the user wants to change.

For protection against accidental operations, the write initiate sequence for NVMKEY must be used to allow any erase or program operation to proceed. After the programming command has been executed, the user application must wait for the programming time until programming is complete. The two instructions following the start of the programming sequence should be `NOP`s.

Refer to **Flash Programming"** (DS70609) in the "*dsPIC33/PIC24 Family Reference Manual*" for details and codes examples on programming using RTSP.

5.4 Flash Memory Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

5.4.1 KEY RESOURCES

- **"Flash Programming"** (DS70609) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

5.5 Control Registers

Four SFRs are used to erase and write the program Flash memory: NVMCON, NVMKEY, NVMADRH and NVMADRL.

The NVMCON register (Register 5-1) enables and initiates Flash memory erase and write operations.

NVMKEY (Register 5-4) is a write-only register that is used for write protection. To start a programming or erase sequence, the user application must consecutively write 0x55 and 0xAA to the NVMKEY register.

There are two NVM Address registers: NVMADRH and NVMADRL. These two registers, when concatenated, form the 24-bit Effective Address (EA) of the selected word for programming operations or the selected page for erase operations.

The NVMADRH register is used to hold the upper 8 bits of the EA, while the NVMADRL register is used to hold the lower 16 bits of the EA.

REGISTER 5-2: NVMADRH: NONVOLATILE MEMORY ADDRESS REGISTER HIGH

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
NVMADR<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-0 **NVMADR<23:16>:** Nonvolatile Memory Write Address High bits

Selects the upper 8 bits of the location to program or erase in program Flash memory. This register may be read or written by the user application.

REGISTER 5-3: NVMADRL: NONVOLATILE MEMORY ADDRESS REGISTER LOW

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
NVMADR<15:8>							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
NVMADR<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **NVMADR<15:0>:** Nonvolatile Memory Write Address Low bits

Selects the lower 16 bits of the location to program or erase in program Flash memory. This register may be read or written by the user application.

REGISTER 5-4: NVMKEY: NONVOLATILE MEMORY KEY

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
NVMKEY<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-0 **NVMKEY<7:0>:** Key Register (write-only) bits

REGISTER 11-7: RPINR12: PERIPHERAL PIN SELECT INPUT REGISTER 12 (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	FLT2R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	FLT1R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**Unimplemented:** Read as ‘`0`’
bit 14-8	**FLT2R<6:0>:** Assign PWM Fault 2 (FLT2) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers) `1111001` = Input tied to RPI121 . . . `0000001` = Input tied to CMP1 `0000000` = Input tied to VSS
bit 7	**Unimplemented:** Read as ‘`0`’
bit 6-0	**FLT1R<6:0>:** Assign PWM Fault 1 (FLT1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers) `1111001` = Input tied to RPI121 . . . `0000001` = Input tied to CMP1 `0000000` = Input tied to VSS

14.0 INPUT CAPTURE

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Input Capture"** (DS70352) in the "*dsPIC33/dsPIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

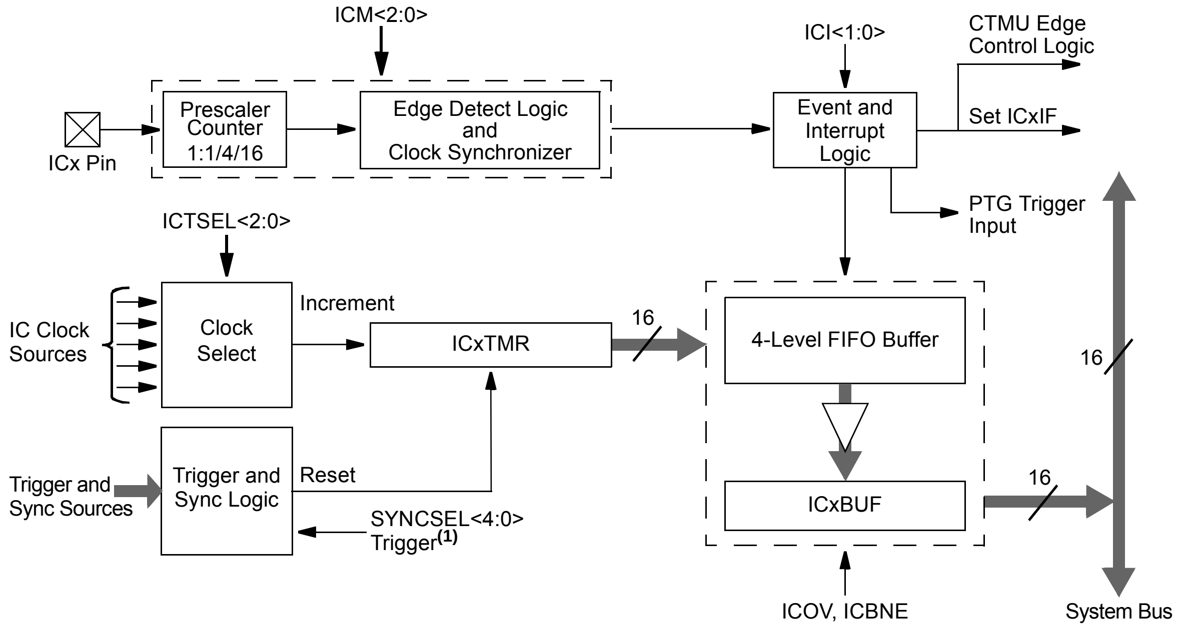
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The input capture module is useful in applications requiring frequency (period) and pulse measurement. The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices support four input capture channels.

Key features of the input capture module include:

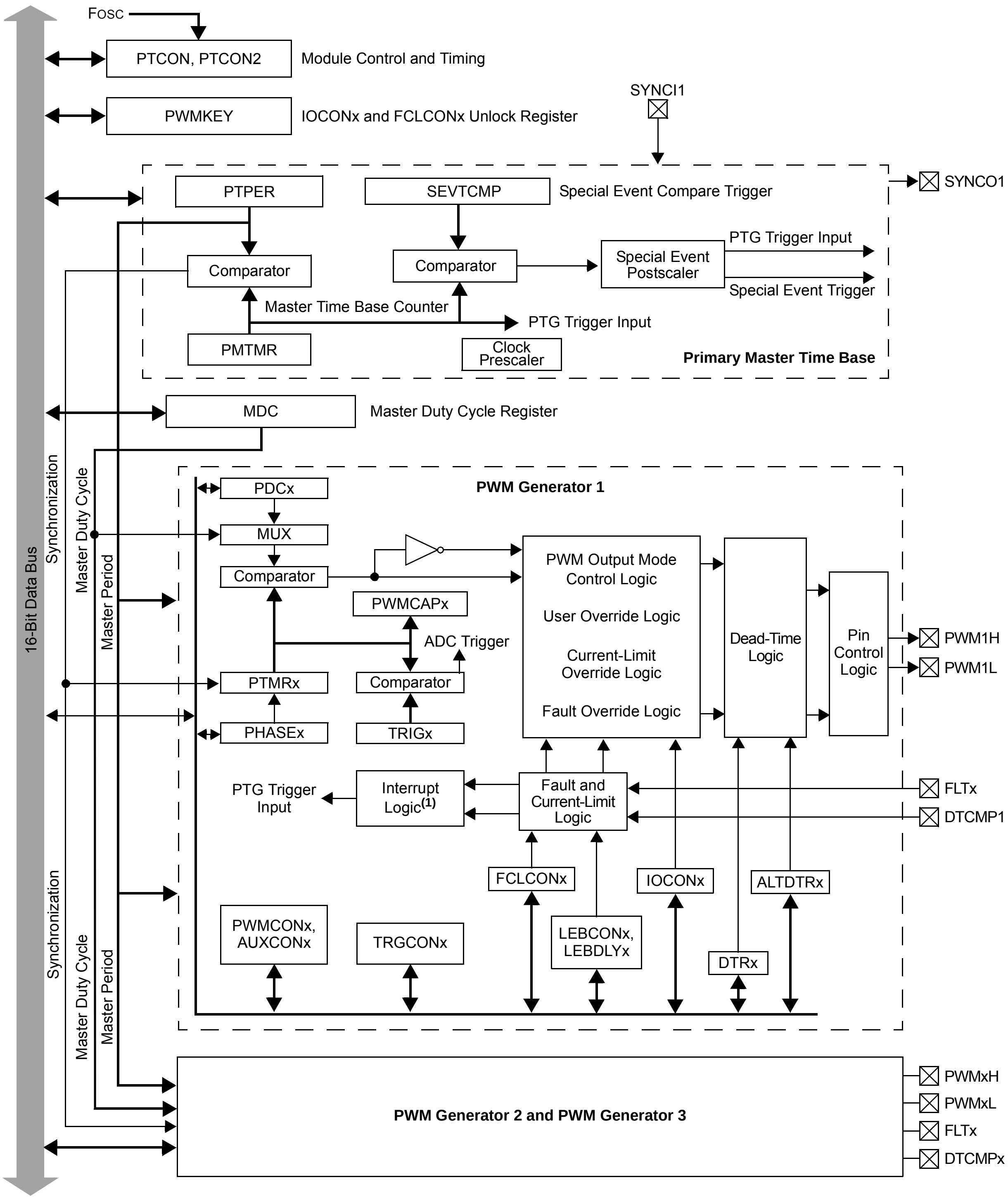
- Hardware-configurable for 32-bit operation in all modes by cascading two adjacent modules
- Synchronous and Trigger modes of output compare operation, with up to 19 user-selectable Trigger/Sync sources available
- A 4-level FIFO buffer for capturing and holding timer values for several events
- Configurable interrupt generation
- Up to six clock sources available for each module, driving a separate internal 16-bit counter

FIGURE 14-1: INPUT CAPTURE x MODULE BLOCK DIAGRAM



Note 1: The Trigger/Sync source is enabled by default and is set to Timer3 as a source. This timer must be enabled for proper ICx module operation or the Trigger/Sync source must be changed to another source option.

FIGURE 16-2: HIGH-SPEED PWMx MODULE REGISTER INTERCONNECTION DIAGRAM



Note 1: The PWM interrupts are generated by logically ORing the FLTSTAT, CLSTAT and TRGSTAT status bits for the given PWM generator. Refer to the "*dsPIC33/PIC24 Family Reference Manual*", **"High-Speed PWM"** (DS70645) for more information.

NOTES:

REGISTER 17-2: QEI1IOC: QEI1 I/O CONTROL REGISTER (CONTINUED)

bit 2	**INDEX:** Status of INDXx Input Pin After Polarity Control `1` = Pin is at logic ‘`1`’ `0` = Pin is at logic ‘`0`’
bit 1	**QEB:** Status of QEBx Input Pin After Polarity Control And SWPAB Pin Swapping `1` = Pin is at logic ‘`1`’ `0` = Pin is at logic ‘`0`’
bit 0	**QEA:** Status of QEAx Input Pin After Polarity Control And SWPAB Pin Swapping `1` = Pin is at logic ‘`1`’ `0` = Pin is at logic ‘`0`’

18.3 SPIx Control Registers

REGISTER 18-1: SPIxSTAT: SPIx STATUS AND CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
SPIEN	—	SPISIDL	—	—	SPIBEC<2:0>		
bit 15							bit 8

R/W-0	R/C-0, HS	R/W-0	R/W-0	R/W-0	R/W-0	R-0, HS, HC	R-0, HS, HC
SRMPT	SPIROV	SRXMPT	SISEL2	SISEL1	SISEL0	SPITBF	SPIRBF
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	HC = Hardware Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **SPIEN:** SPIx Enable bit

1 = Enables the module and configures SCKx, SDOx, SDIx and $\overline{\text{SSx}}$ as serial port pins
0 = Disables the module

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **SPISIDL:** SPIx Stop in Idle Mode bit

1 = Discontinues the module operation when device enters Idle mode
0 = Continues the module operation in Idle mode

bit 12-11 **Unimplemented:** Read as ‘0’

bit 10-8 **SPIBEC<2:0>:** SPIx Buffer Element Count bits (valid in Enhanced Buffer mode)

Master mode:
Number of SPIx transfers that are pending.

Slave mode:
Number of SPIx transfers that are unread.

bit 7 **SRMPT:** SPIx Shift Register (SPIxSR) Empty bit (valid in Enhanced Buffer mode)

1 = SPIx Shift register is empty and Ready-To-Send or receive the data
0 = SPIx Shift register is not empty

bit 6 **SPIROV:** SPIx Receive Overflow Flag bit

1 = A new byte/word is completely received and discarded; the user application has not read the previous data in the SPIxBUF register
0 = No overflow has occurred

bit 5 **SRXMPT:** SPIx Receive FIFO Empty bit (valid in Enhanced Buffer mode)

1 = RX FIFO is empty
0 = RX FIFO is not empty

bit 4-2 **SISEL<2:0>:** SPIx Buffer Interrupt Mode bits (valid in Enhanced Buffer mode)

111 = Interrupt when the SPIx transmit buffer is full (SPITBF bit is set)
110 = Interrupt when last bit is shifted into SPIxSR and as a result, the TX FIFO is empty
101 = Interrupt when the last bit is shifted out of SPIxSR and the transmit is complete
100 = Interrupt when one data is shifted into the SPIxSR and as a result, the TX FIFO has one open memory location
011 = Interrupt when the SPIx receive buffer is full (SPIRBF bit is set)
010 = Interrupt when the SPIx receive buffer is 3/4 or more full
001 = Interrupt when data is available in the receive buffer (SRMPT bit is set)
000 = Interrupt when the last data in the receive buffer is read and as a result, the buffer is empty (SRXMPT bit is set)

REGISTER 18-2: SPIxCON1: SPIx CONTROL REGISTER 1 (CONTINUED)

bit 4-2	**SPRE<2:0>:** Secondary Prescale bits (Master mode)(3) `111` = Secondary prescale 1:1 `110` = Secondary prescale 2:1 • • • `000` = Secondary prescale 8:1
bit 1-0	**PPRE<1:0>:** Primary Prescale bits (Master mode)(3) `11` = Primary prescale 1:1 `10` = Primary prescale 4:1 `01` = Primary prescale 16:1 `00` = Primary prescale 64:1

Note 1: The CKE bit is not used in Framed SPI modes. Program this bit to ‘`0`’ for Framed SPI modes (FRMEN = `1`).

2: This bit must be cleared when FRMEN = `1`.

3: Do not set both primary and secondary prescalers to the value of 1:1.

22.2 CTMU Control Registers

REGISTER 22-1: CTMUCON1: CTMU CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CTMUEN	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN[1]	CTTRIG
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CTMUEN:** CTMU Enable bit

1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **CTMUSIDL:** CTMU Stop in Idle Mode bit

1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **TGEN:** Time Generation Enable bit

1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit

1 = Hardware modules are used to trigger edges (TMRx, CTEDx, etc.)
0 = Software is used to trigger edges (manual set of EDGxSTAT)

bit 10 **EDGSEQEN:** Edge Sequence Enable bit

1 = Edge 1 event must occur before Edge 2 event can occur
0 = No edge sequence is needed

bit 9 **IDISSEN:** Analog Current Source Control bit[1]

1 = Analog current source output is grounded
0 = Analog current source output is not grounded

bit 8 **CTTRIG:** ADC Trigger Control bit

1 = CTMU triggers ADC start of conversion
0 = CTMU does not trigger ADC start of conversion

bit 7-0 **Unimplemented:** Read as ‘0’

Note 1: The ADC module Sample-and-Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitance measurement must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to ‘1’, performs this function. The ADC must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

TABLE 30-57: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of: VDD – 0.3 or 3.0	—	Lesser of: VDD + 0.3 or 3.6	V	
AD02	AVSS	Module VSS Supply	VSS – 0.3	—	VSS + 0.3	V	
Reference Inputs							
AD05	VREFH	Reference Voltage High	AVSS + 2.5	—	AVDD	V	VREFH = VREF+ VREFL = VREF- **(Note 1)**
AD05a			3.0	—	3.6	V	VREFH = AVDD VREFL = AVSS = 0
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD – 2.5	V	**(Note 1)**
AD06a			0	—	0	V	VREFH = AVDD VREFL = AVSS = 0
AD07	VREF	Absolute Reference Voltage	2.5	—	3.6	V	VREF = VREFH - VREFL
AD08	IREF	Current Drain	— —	— —	10 600	μA μA	ADC off ADC on
AD09	IAD	Operating Current(2)	—	5	—	mA	ADC operating in 10-bit mode **(Note 1)**
			—	2	—	mA	ADC operating in 12-bit mode **(Note 1)**
Analog Input							
AD12	VINH	Input Voltage Range VINH	VINL	—	VREFH	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), positive input
AD13	VINL	Input Voltage Range VINL	VREFL	—	AVSS + 1V	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), negative input
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	200	Ω	Impedance to achieve maximum performance of ADC

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Parameter is characterized but not tested in manufacturing.

TABLE 30-59: ADC MODULE SPECIFICATIONS (10-BIT MODE)

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
			ADC Accuracy (10-Bit Mode)				
AD20b	Nr	Resolution	10 Data Bits			bits	
AD21b	INL	Integral Nonlinearity	-0.625	—	0.625	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-1.5	—	1.5	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD22b	DNL	Differential Nonlinearity	-0.25	—	0.25	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-0.25	—	0.25	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD23b	GERR	Gain Error	-2.5	—	2.5	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-2.5	—	2.5	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD24b	EOFF	Offset Error	-1.25	—	1.25	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-1.25	—	1.25	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD25b	—	Monotonicity	—	—	—	—	Guaranteed
			Dynamic Performance (10-Bit Mode)				
AD30b	THD	Total Harmonic Distortion(3)	—	64	—	dB	
AD31b	SINAD	Signal to Noise and Distortion(3)	—	57	—	dB	
AD32b	SFDR	Spurious Free Dynamic Range(3)	—	72	—	dB	
AD33b	FNYQ	Input Signal Bandwidth(3)	—	550	—	kHz	
AD34b	ENOB	Effective Number of Bits(3)	—	9.4	—	bits	

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

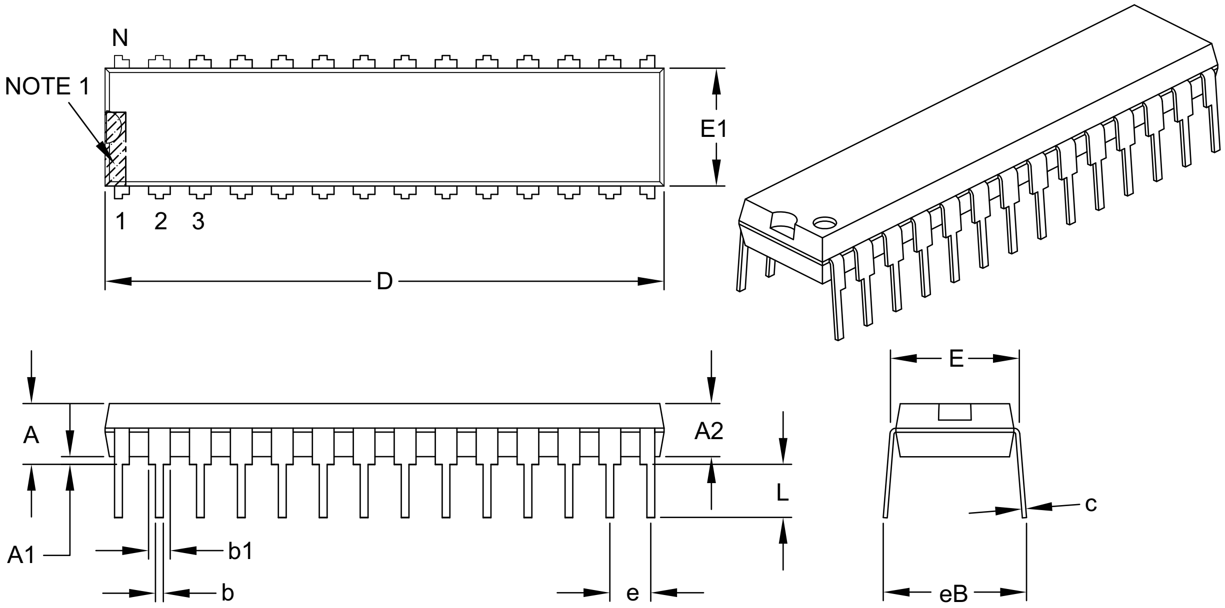
2: For all accuracy specifications, VINL = AVSS = VREFL = 0V and AVDD = VREFH = 3.6V.

3: Parameters are characterized but not tested in manufacturing.

33.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	INCHES		
	Dimension Limits	MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

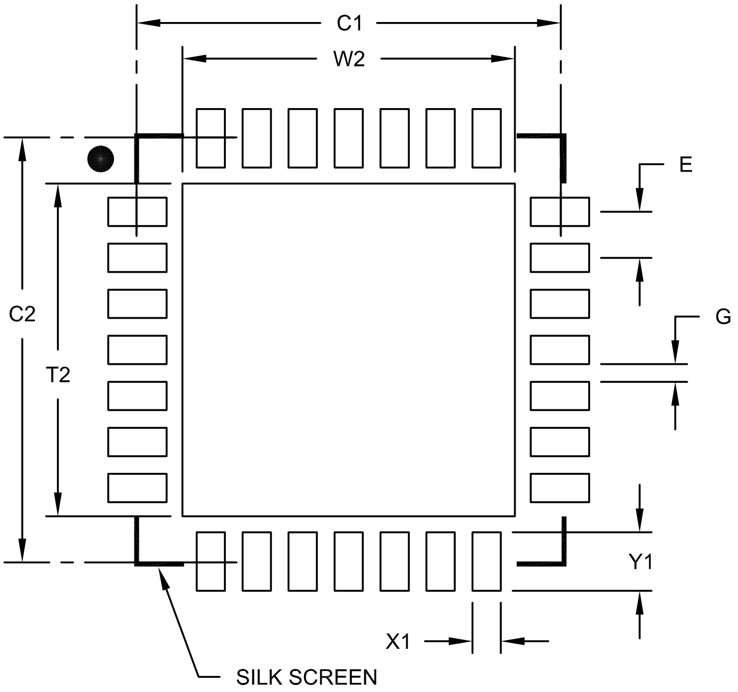
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.70
Optional Center Pad Length	T2			4.70
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.40
Contact Pad Length (X28)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

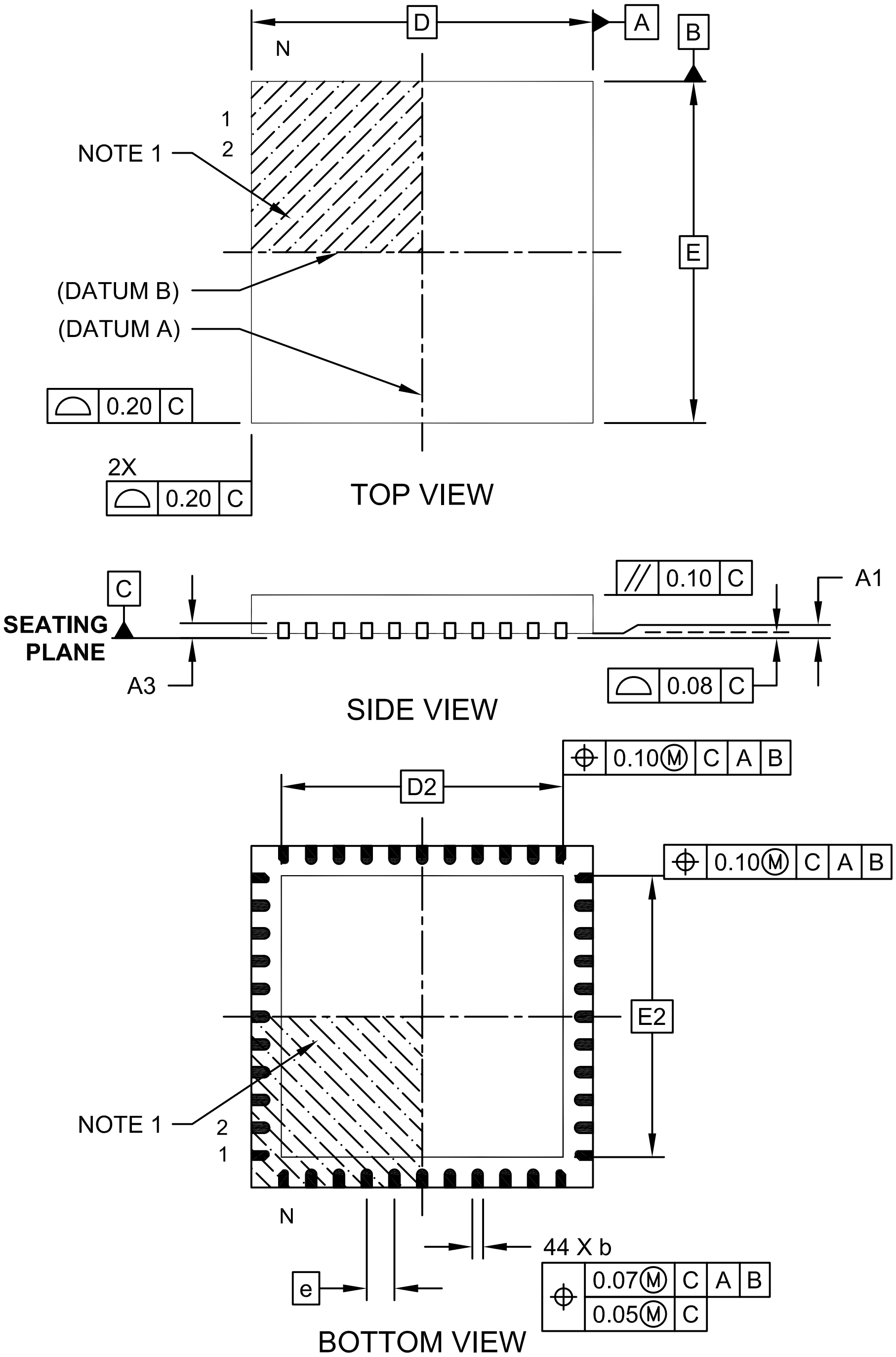
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2124A

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-103C Sheet 1 of 2